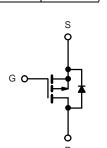


## P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY							
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)				
	0.055 at V <sub>GS</sub> = - 4.5 V	- 6 <sup>a</sup>					
- 20	0.060 at V <sub>GS</sub> = - 3.6 V	- 5.8 <sup>a</sup>	12 nC				
	0.065 at V <sub>GS</sub> = - 2.5 V	- 5.6 <sup>a</sup>					

D





#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS

#### **APPLICATIONS**

- · Portable Devices
  - Load Switch
  - Charger Switch
  - Battery Switch
  - DC/DC Converter

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V <sub>DS</sub>	- 20	V			
Gate-Source Voltage	$V_{GS}$	± 12	V			
	T <sub>C</sub> = 25 °C		- 6 <sup>a</sup>			
Continuous Prain Current (T. – 150 °C)	T <sub>C</sub> = 70 °C		- 5 <sup>a</sup>			
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 5 <sup>a, b, c</sup>			
	T <sub>A</sub> = 70 °C		- 4.2 <sup>b, c</sup>	Α		
Pulsed Drain Current		I <sub>DM</sub>	- 18			
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	I <sub>S</sub>	- 4.8			
Continuous Source-Diam Diode Current	T <sub>A</sub> = 25 °C		- 1.9 <sup>b, c</sup>			
	T <sub>C</sub> = 25 °C		6			
Maximum Pawar Dingination	T <sub>C</sub> = 70 °C	- P <sub>D</sub>	3	W		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		2.3 <sup>b, c</sup>	VV		
	T <sub>A</sub> = 70 °C		1.2 <sup>b, c</sup>			
Operating Junction and Storage Temperature Rai	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C			
Soldering Recommendations (Peak Temperature)		260	C			

THERMAL RESISTANCE RATINGS								
Parameter	Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient	t ≤ 5 s	R <sub>thJA</sub>	45	55	°C/W			
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	18	22	- C/VV			

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = - 250 μA	- 20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J. 050 A		- 14		) 1/06	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		3.2		mV/°	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 0.5		- 1.4	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V			- 1	μА	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C			- 5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 20			Α	
	, ,	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 4.9 A		0.055		Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 3.6 V, I <sub>D</sub> = - 4.6 A		0.060			
	, ,	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 2.0 A		0.065			
Forward Transconductance <sup>a</sup> g <sub>fs</sub>		V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 4.9 A		16		S	
Dynamic <sup>b</sup>	•						
Input Capacitance	C <sub>iss</sub>			1000		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		225			
Reverse Transfer Capacitance	C <sub>rss</sub>			195			
T. 10 . 0		V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 6.5 A		25	38		
Total Gate Charge	Q <sub>g</sub>			12.5	19	nC	
Gate-Source Charge		V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 6.5 A		2			
Gate-Drain Charge	Q <sub>gd</sub>			4			
Gate Resistance	R <sub>q</sub>	f = 1 MHz	0.9	4.6	9.2	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			25	50		
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V}, R_{L} = 1.9 \Omega$		20	40	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong -5.2 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		30	60		
Fall Time	t <sub>f</sub>			12	25		
Turn-On Delay Time	t <sub>d(on)</sub>			10	20		
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V, R}_{1} = -1.9 \Omega$		10	20		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong -5.2 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		27	55		
Fall Time	t <sub>f</sub>			12	25	1	
<b>Drain-Source Body Diode Characteristic</b>	1						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 6		
Pulse Diode Forward Current	I <sub>SM</sub>	-			- 20	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 5.2 A, V <sub>GS</sub> = 0 V		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			20	40	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			10	20	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -5.2 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 °C$		10			
Reverse Recovery Rise Time		t <sub>b</sub>		10		ns	

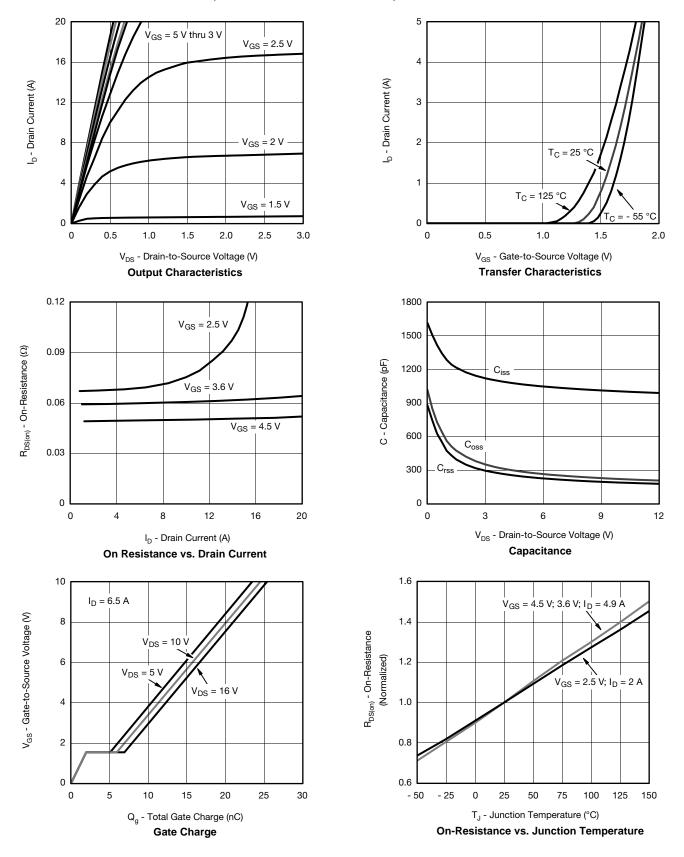
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$  b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

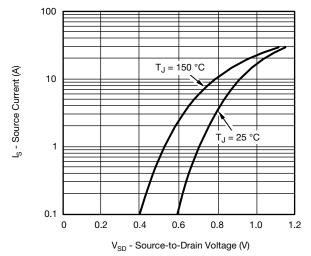
服务热线:400-655-8788



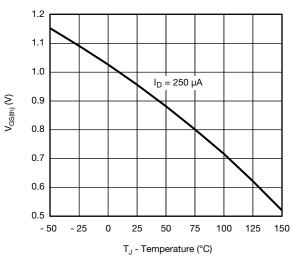


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© 0.08 0.06 0.04 0.02 0.04 T<sub>J</sub> = 125 °C

2

0.12

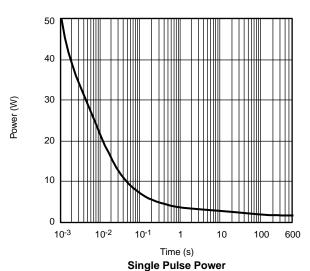
0.10

0

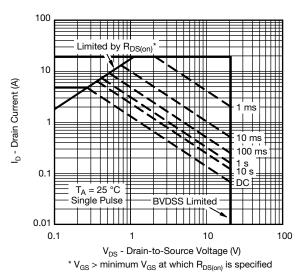
I<sub>D</sub> = 4.9 A

3

5

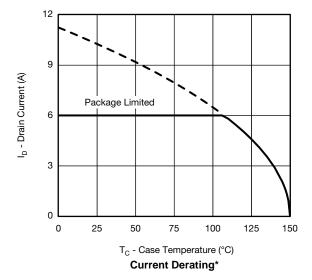


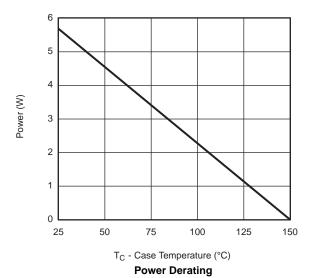




Safe Operating Area, Junction-to-Ambient



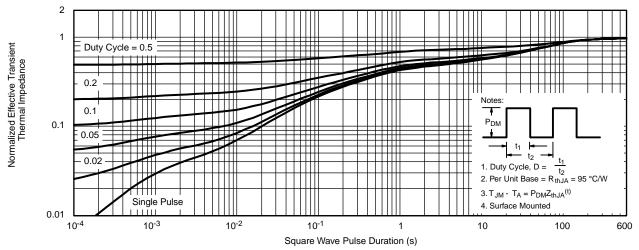




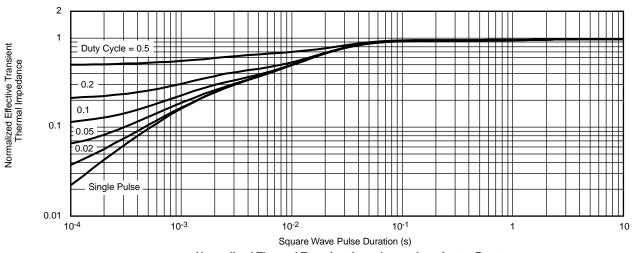
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<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





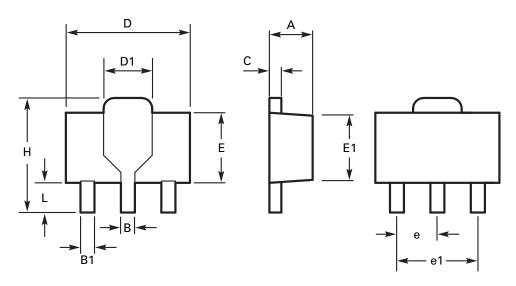
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



### Package outline - SOT89



DIM	Millin	neters	Inc	Inches DIM Millimeters Inc		Inches DIM Millimeters Inches		DIM Millimeters		hes
	Min	Max	Min	Max		Min	Max	Min	Max	
Α	1.40	1.60	0.550	0.630	Е	2.29	2.60	0.090	0.102	
В	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090	
B1	0.36	0.48	0.014	0.019	е	1.50 BSC		0.059 BSC		
С	0.35	0.44	0.014	0.017	e1	3.00 BSC		0.118 BSC		
D	4.40	4.60	0.173	0.181	Н	3.94	4.25	0.155	0.167	
D1	1.62	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047	

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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